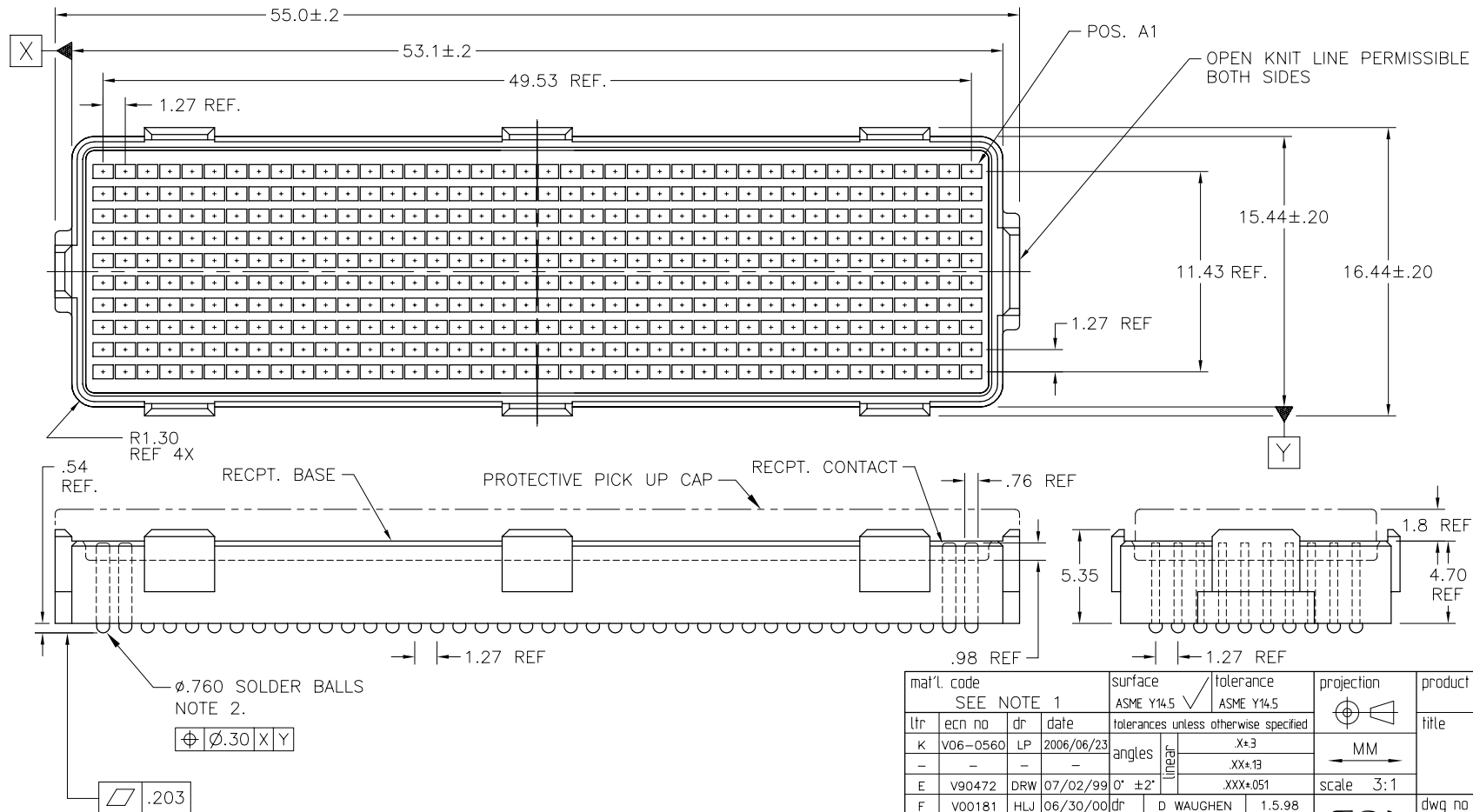
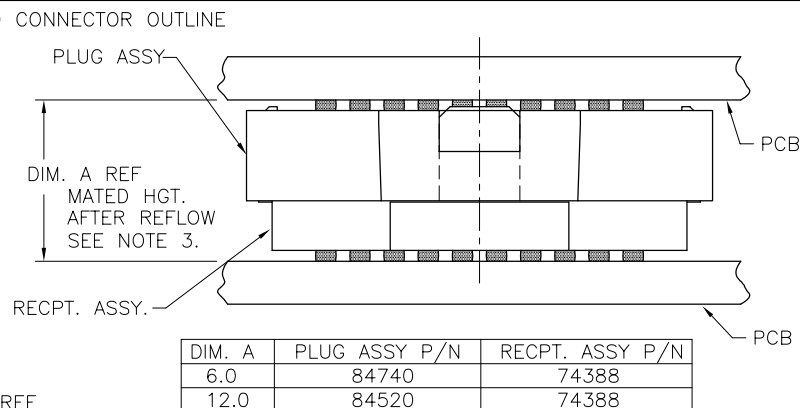
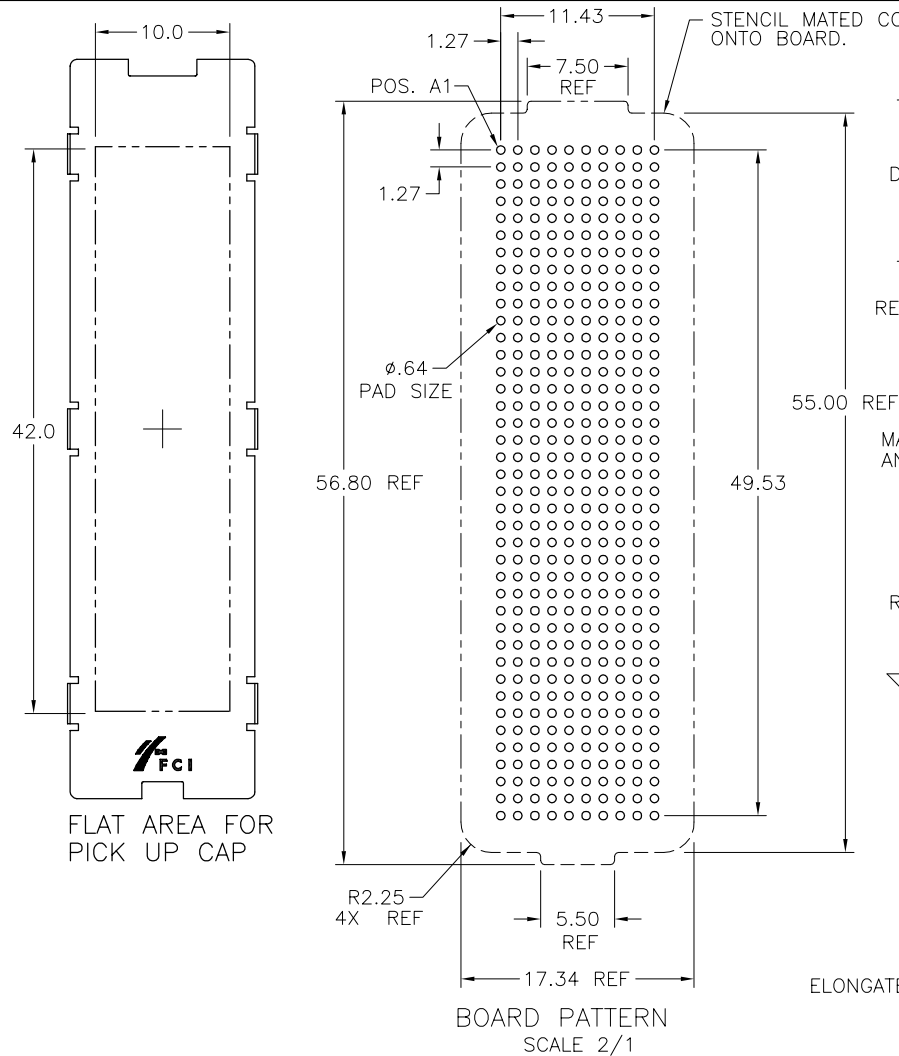


PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74388-001	YES	15u" (.38u") Au OVER Ni	SnPb
74388-001LF			SnAgCu LEAD FREE (5)(6)
74388-101	YES	30u" (.76u") Au OVER Ni	SnPb
74388-101LF			SnAgCu LEAD FREE (5)(6)
74388-201	YES	SEE NOTE 4.	SnPb
74388-201LF			SnAgCu LEAD FREE (5)(6)

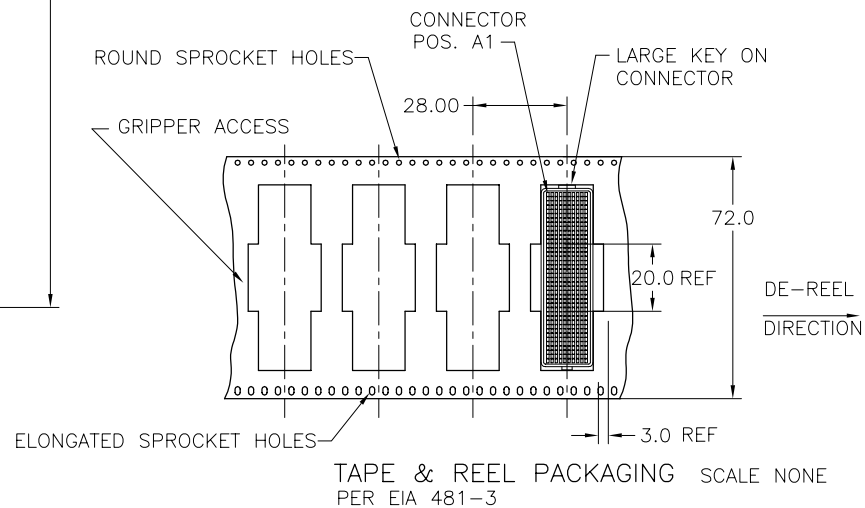


mat'l. code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
ltr	ecr no	dr	date	tolerances unless otherwise specified			MEG-ARRAY
K	V06-0560	LP	2006/06/23	angles	X*3	MM	title
-	-	-	-	line to	.XX*13		6mm RECEPT. ASSY
E	V90472	DRW	07/02/99	0° ± 2°	XXX*051	scale 3:1	10 X 40= 400 POS.
F	V00181	HLJ	06/30/00	dr	D WAUGHEN	1.5.98	dwg no
G	V20006	DRW	01/07/02	engr	T LEMKE	1.5.98	sheet 1 of 3
H	V03-0679	DAI	06/19/03	chr	T LEMKE	1.5.98	74388
J	V04-0940	VS	10/18/04	appd	T LEMKE	1.5.98	A4
sheet	revision	K	K	K			type
index	sheet	1	2	3			CUSTOMER Drawing



MATED HEIGHT AFTER REFLOW IS BASED ON $\phi .64$ mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW – MATED CONNECTORS SCALE NONE



mat'l. code SEE NOTE 1	surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕	product family MEG-ARRAY
ltr	ecr no	dr	date	title 6mm RECPT. ASSY. 10x40= 400 POS.
k				scale 2:1
		angles	line	FCI
		0° ±2°	XXX+051	type CUSTOMER Drawing
		dr	D WAUGHEN	1.5.98
		enr	T LEMKE	1.5.98
		chr	T LEMKE	1.5.98
		appd	T LEMKE	1.5.98
sheet index	revision sheet			

NOTES:①. MAT'L:HOUSING: LCPCONTACT: COPPER ALLOYPLATING

CONTACT: (SEE TABLE ON SHEET1)

SOLDER BALL: (SEE TABLE ON SHEET1)

EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Ag/0.5Cu

- ②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY											
ltr		ecn no		dr		date		tolerances unless otherwise specified										title			
K								angles		linear	X*3										
											XX*13										
											XXX*051										
								0° ±2°			scale 2:1										
								dr		D WAUGHEN		1.5.98				dwg no		sheet 3 of 3		size	
								engr		T LEMKE		1.5.98				74388		A4			
								chr		T LEMKE		1.5.98									
								appd		T LEMKE		1.5.98									
sheet index		revision sheet																			